SPECIFICATION

TITLE:NOVEL IMMUNOTHERAPY AGAINST SEVERAL TUMORS INCLUDING GASTROINTESTINAL AND GASTRIC CANCER

TECHNICAL FIELD

[0001] The present invention relates to a resin composition sheet. Moreover, the present invention relates to a method for molding a resin composition sheet.

BACKGROUND ART

[0002] A "sheet material formed from a blend obtained by blending amorphous polyester resin with polycarbonate resin" has been proposed in the past (for example, see Japanese Unexamined Patent Publication No. 2004-91691). Thus, such a sheet material can serve in the manufacture of product packaging such as carrier tapes, and the like.
their molding temperatures can be lowered from 260-280 °C to 200-250 °C, and the users of such sheet materials can contribute to reducing energy expenditures.

PRIOR ART LITERATURE

PATENT LITERATURE

[0003] Patent Document 1: Japanese Unexamined Patent Publication No. 2004-91691

SUMMARY OF THE INVENTION

PROBLEM TO BE SOLVED BY THE INVENTION

[0004] However, when such sheet materials are heated to temperatures in the vicinity of 200-250 °C using a contact type heating device, the shape of the mold-releasing film (e.g., Teflon®) that is mounted on a heating platen of the contact heating device can give rise to a poor appearance being transferred to the sheet materials.
For this problem, it is believed that the countermeasure is due to the preset temperature for the heating platen being relatively low, which by itself is frequently the reason why sufficient precise molding is not obtained.

[0005] The object of the present invention is to provide a resin composition sheet that when used in the manufacture of product packaging such as carrier tapes, and the like.
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